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- Operating Range of 2 V to 5.5 V
- Max t<sub>pd</sub> of 6 ns at 5 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 5 V

# DBV OR DCK PACKAGE (TOP VIEW) OE 1 5 VCC

GND [

### description/ordering information

The SN74AHC1G125 is a single bus buffer gate/line driver with 3-state output. The output is disabled when the output-enable  $(\overline{OE})$  input is high. When  $\overline{OE}$  is low, true data is passed from the A input to the Y output.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### ORDERING INFORMATION

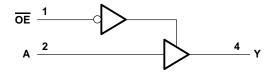
TA	PACKAGE	<u> </u>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>‡</sup>	
	SOT (SOT-23) – DBV	Reel of 3000	SN74AHC1G125DBVR	A25	
–40°C to 85°C	301 (301-23) – DBV	Reel of 250	SN74AHC1G125DBVT	A25_	
	SOT (SC-70) – DCK	Reel of 3000	SN74AHC1G125DCKR	AM	
	301 (30-70) - DCK	Reel of 250	SN74AHC1G125DCKT	Alvi_	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

INPU	JTS	OUTPUT
OE	Α	Y
L	Н	Н
L	L	L
Н	Χ	Z

### logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> The actual top-side marking has one additional character that designates the assembly/test site.

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DBV package .	206°C/W
DCK package .	252°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
	$V_{CC} = 2 V$		1.5		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 2 V		0.5	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65	
٧ <sub>I</sub>	Input voltage		0	5.5	V
٧o	Output voltage		0	VCC	V
		V <sub>CC</sub> = 2 V		-50	μΑ
loh	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	A
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V <sub>CC</sub> = 2 V		50	μΑ
loL	Low-level output current	V <sub>CC</sub> = 3.3 V ± 0.3 V	4 8		mA
		$V_{CC} = 5 V \pm 0.5 V$			
A+/A	lanut transition rice or fell rate	V <sub>CC</sub> = 3.3 V ± 0.3 V		100	22/1
Δt/Δv	Input transition rise or fall rate $V_{CC} = 5 \text{ V} \pm$			20	ns/V
T <sub>A</sub>	Operating free-air temperature	-	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T <sub>A</sub> = 25°C			MINI	MAY	LINUT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		
	I <sub>OH</sub> = -50 μA	3 V	2.9	3		2.9		
Voн		4.5 V	4.4	4.5		4.4		V
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
V <sub>OL</sub>		4.5 V			0.1		0.1	V
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.44	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.44	
lį	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
loz	$V_I = V_{CC}$ or GND	5.5 V			±0.25		±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10	μΑ
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10		10	pF
Co	$V_O = V_{CC}$ or GND	5 V		10				pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	TO LOAD		5°C	MIN	MAX	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN TY	P MAX	IVIIIV	WAX	UNIT	
<sup>t</sup> PLH	А	Y	C <sub>L</sub> = 15 pF	5	6 8	1	9.5	ns	
t <sub>PHL</sub>	٨	•	OL = 13 pr	5	6 8	1	9.5	115	
<sup>t</sup> PZH	ŌĒ	Y	C <sub>L</sub> = 15 pF	5	4 8	1	9.5	ns	
t <sub>PZL</sub>	OE .	CL = 15 pr	CL = 15 pr	5	4 8	1	9.5	115	
<sup>t</sup> PHZ	ŌĒ	Y	C <sub>L</sub> = 15 pF		7 9.7	1	11.5	ns	
tPLZ	OE	T	OL = 13 pr		7 9.7	1	11.5	115	
<sup>t</sup> PLH	А	Y	C: -50 pE	8	1 11.5	1	13	ns	
<sup>t</sup> PHL	A	ı	C <sub>L</sub> = 50 pF	8	1 11.5	1	13	115	
<sup>t</sup> PZH	ŌĒ	Y	C <sub>L</sub> = 50 pF	7	9 11.5	1	13	ns	
t <sub>PZL</sub>	OE	ī	OL = 50 pr	7	9 11.5	1	13	115	
t <sub>PHZ</sub>	ŌĒ	Y	C <sub>L</sub> = 50 pF	9	5 13.2	1	15	no	
<sup>t</sup> PLZ	OE .	Y	Y	CL = 50 pr	9	5 13.2	1	15	ns

### SN74AHC1G125 SINGLE BUS BUFFER GATE WITH 3-STATE OUTPUT

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

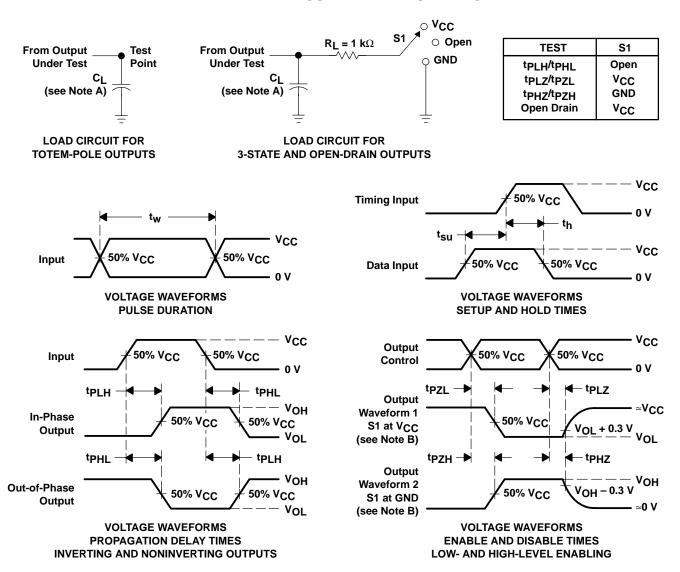
PARAMETER	FROM	то			<b>Վ = 25°C</b>	;	MIN	MAX	UNIT												
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	WAX	UNIT												
<sup>t</sup> PLH	А	Y	C <sub>L</sub> = 15 pF		3.8	5.5	1	6.5	ns												
<sup>t</sup> PHL	A	ı	O[ = 13 pr		3.8	5.5	1	6.5	115												
<sup>t</sup> PZH	<u>OE</u>	Y	C <sub>L</sub> = 15 pF		3.6	5.1	1	6	ns												
<sup>t</sup> PZL	OE	' I	<b>'</b>	ľ	ı	'	ī	Ť	ī	Ť	ī	'	'	'	CL = 15 pr		3.6	5.1	1	6	115
<sup>t</sup> PHZ	ŌĒ	Y	C <sub>L</sub> = 15 pF		4.6	6.8	1	8	ns												
<sup>t</sup> PLZ	OL	'	OL = 13 pr		4.6	6.8	1	8	115												
<sup>t</sup> PLH	Δ	Y	C: 50 pF		5.3	7.5	1	8.5													
<sup>t</sup> PHL	А	CL = 50 pr	C <sub>L</sub> = 50 pF		5.3	7.5	1	8.5	ns												
<sup>t</sup> PZH	ŌĒ	Y	C: - 50 pF		5.1	7.1	1	8	no												
<sup>t</sup> PZL	OE	Ť	Ť	l r	, r	<b>'</b>	C <sub>L</sub> = 50 pF		5.1	7.1	1	8	ns								
<sup>t</sup> PHZ	ŌĒ	Y	C <sub>L</sub> = 50 pF		6.1	8.8	1	10	ns												
t <sub>PLZ</sub>	OE .	ſ	OL = 50 pr		6.1	8.8	1	10	115												

# operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	14	pF



### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







i.com 25-Feb-2005

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC1G125DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G125DBVT	ACTIVE	SOT-23	DBV	5	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G125DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC1G125DCKT	ACTIVE	SC70	DCK	5	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

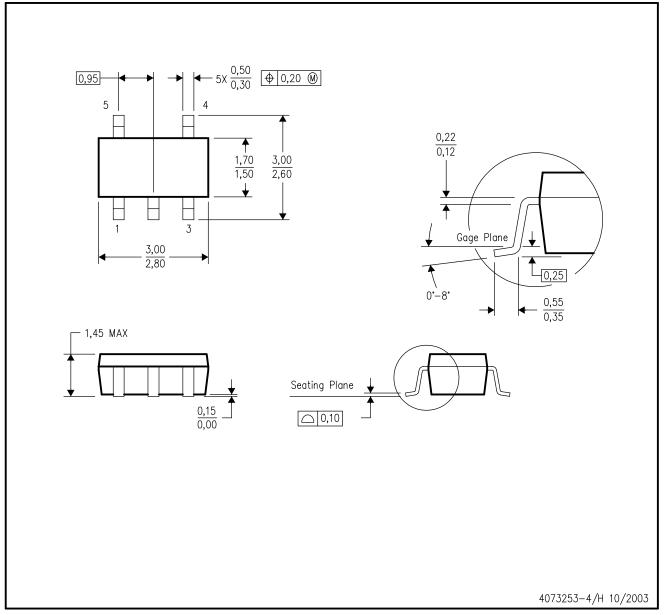
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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# DBV (R-PDSO-G5)

# PLASTIC SMALL-OUTLINE PACKAGE



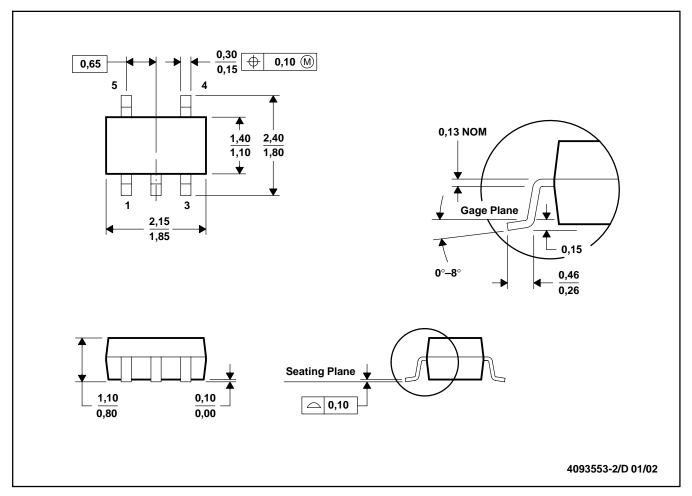
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



### DCK (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

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